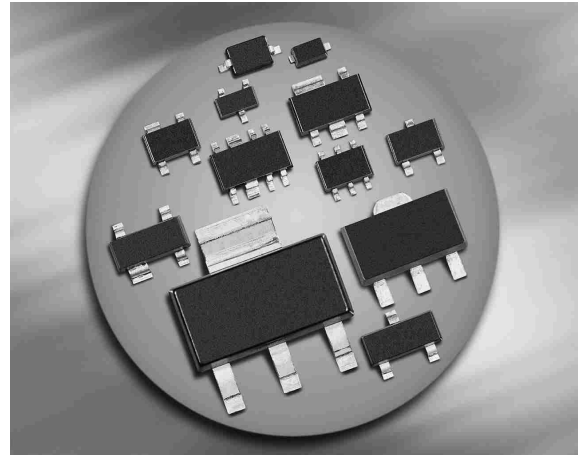
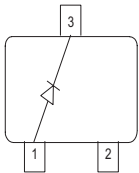
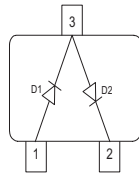
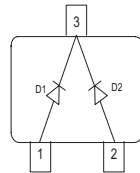
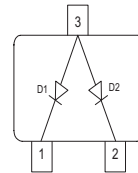
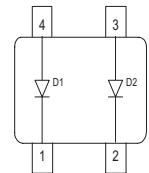


**Silicon Schottky Diode**

- For mixer applications in VHF/UHF range
- For high-speed switching application
- Pb-free (RoHS compliant) package


**BAT17**

**BAT17-04  
BAT17-04W**

**BAT17-05  
BAT17-05W**

**BAT17-06W**

**BAT17-07**


**ESD (Electrostatic discharge) sensitive device, observe handling precaution!**

Type	Package	Configuration	$L_S$ (nH)	Marking
BAT17	SOT23	single	1.8	53s
BAT17-04	SOT23	series	1.8	54s
BAT17-04W	SOT323	series	1.4	54s
BAT17-05	SOT23	common cathode	1.8	55s
BAT17-05W	SOT323	common cathode	1.4	55s
BAT17-06W	SOT323	common anode	1.4	56s
BAT17-07	SOT143	parallel pair	2	57s

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	4	V
Forward current	$I_F$	130	mA
Total power dissipation	$P_{\text{tot}}$		mW
BAT17, $T_S \leq 77^\circ\text{C}$		150	
BAT17-04, $T_S \leq 61^\circ\text{C}$		150	
BAT17-05, $T_S \leq 46^\circ\text{C}$		150	
BAT17-04W, -05W, -6W, $T_S \leq 92^\circ\text{C}$		150	
BAT17-07, $T_S \leq 60^\circ\text{C}$		150	
Junction temperature	$T_j$	150	°C
Operating temperature range	$T_{\text{op}}$	-55 ... 125	
Storage temperature	$T_{\text{stg}}$	-55 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{\text{thJS}}$		K/W
BAT17		$\leq 490$	
BAT17-04, BAT17-07		$\leq 590$	
BAT17-05		$\leq 690$	
BAT17-04W, BAT17-05W, BAT17-06W		$\leq 390$	

<sup>1)</sup>For calculation of  $R_{\text{thJA}}$  please refer to Application Note Thermal Resistance

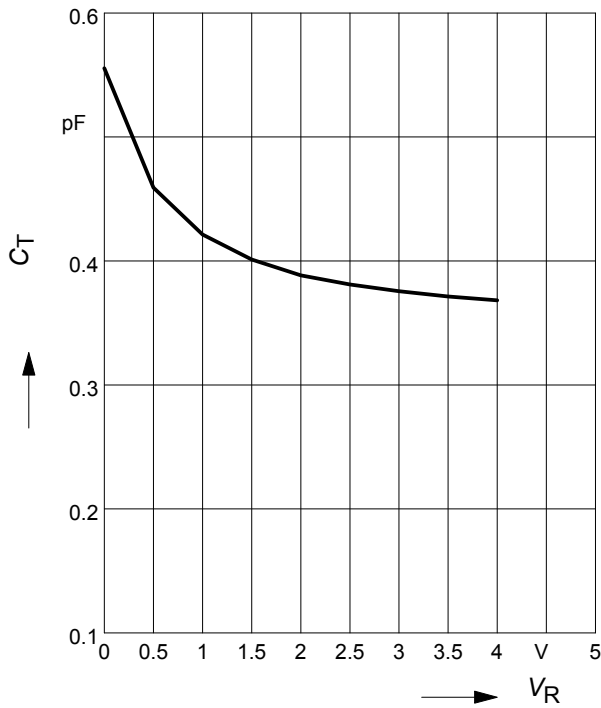
**Electrical Characteristics at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Breakdown voltage $I_{(BR)} = 10 \mu\text{A}$	$V_{(BR)}$	4	-	-	V
Reverse current $V_R = 3 \text{ V}$ $V_R = 4 \text{ V}$ $V_R = 3 \text{ V}, T_A = 60^\circ\text{C}$	$I_R$	-	-	0.25 10 1.25	$\mu\text{A}$
Forward voltage $I_F = 0.1 \text{ mA}$ $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$	$V_F$	200 250 350	275 340 425	350 450 600	mV
Forward voltage matching <sup>1)</sup> $I_F = 1 \text{ mA}$	$\Delta V_F$	-	-	20	
<b>AC Characteristics</b>					
Diode capacitance $V_R = 0, f = 1 \text{ MHz}$	$C_T$	0.4	0.55	0.75	pF
Differential forward resistance $I_F = 5 \text{ mA}, f = 10 \text{ kHz}$	$R_F$	-	8	15	$\Omega$

<sup>1)</sup> $\Delta V_F$  is the difference between lowest and highest  $V_F$  in multiple diode component.

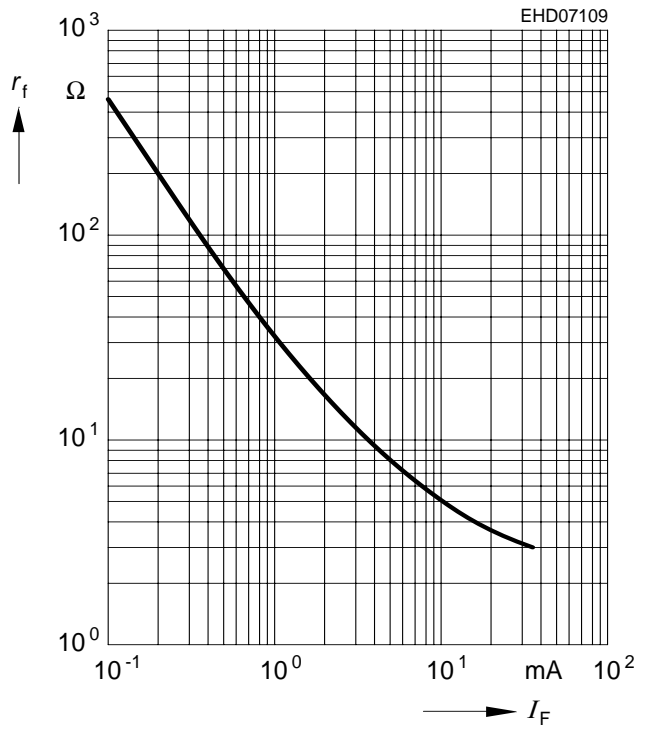
**Diode capacitance  $C_T = f(V_R)$**

$f = 1\text{MHz}$



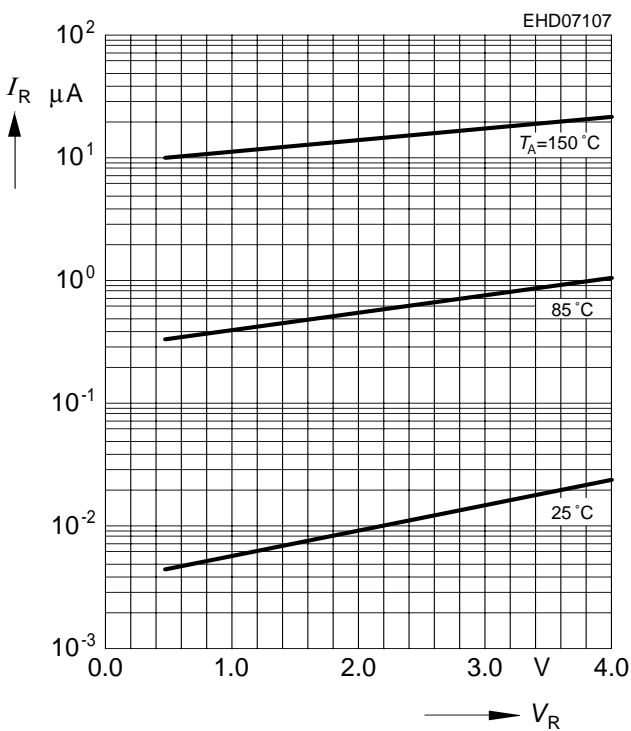
**Forward resistance  $r_f = f(I_F)$**

$f = 10\text{kHz}$



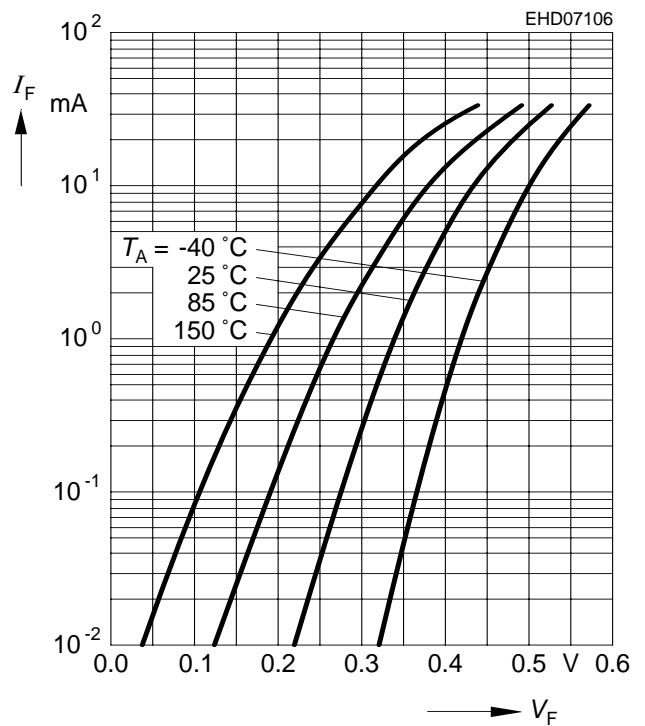
**Reverse current  $I_R = f(V_R)$**

$T_A = \text{Parameter}$



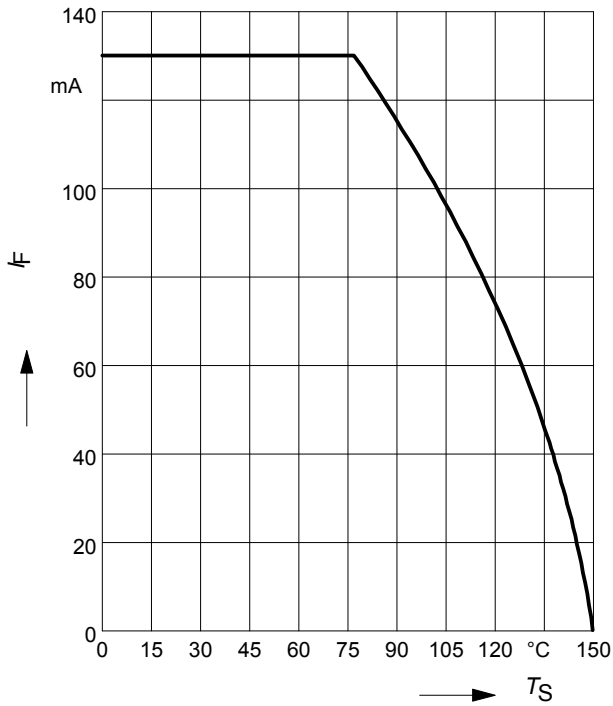
**Forward current  $I_F = f(V_F)$**

$T_A = \text{Parameter}$



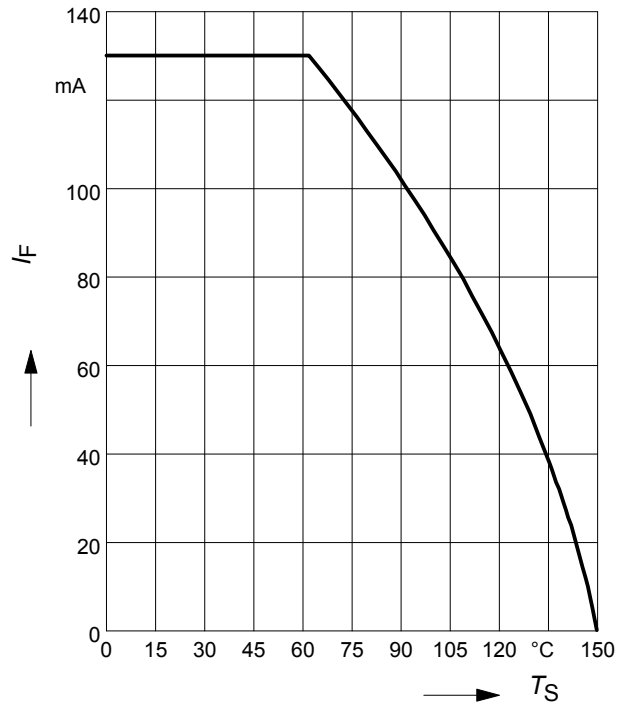
**Forward current  $I_F = f(T_S)$**

BAT17



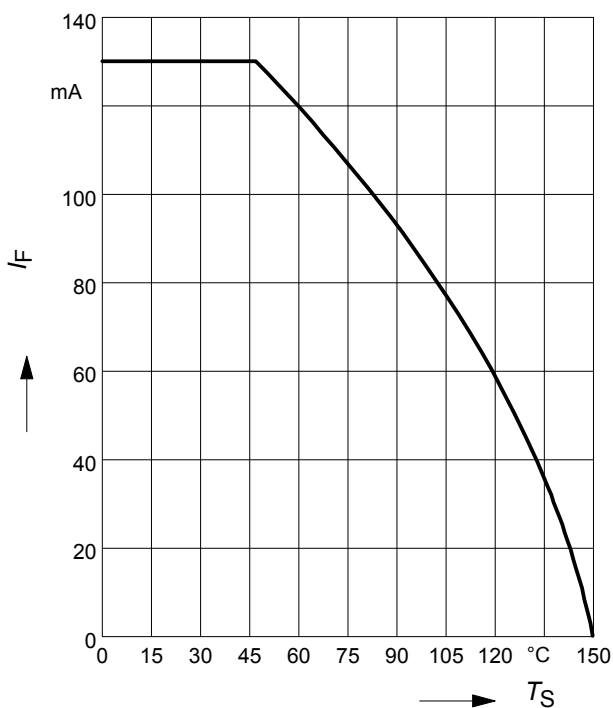
**Forward current  $I_F = f(T_S)$**

BAT17-04, BAT17-07

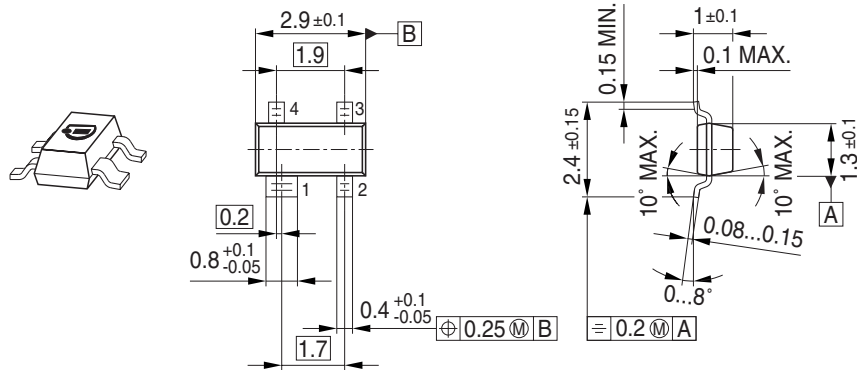


**Forward current  $I_F = f(T_S)$**

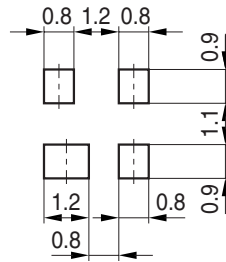
BAT17-05



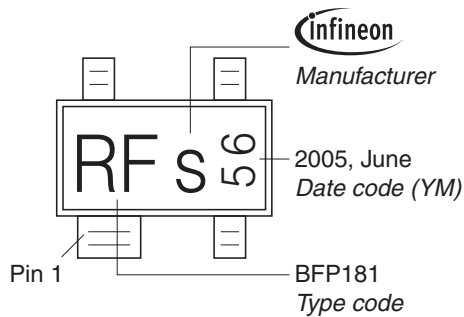
Package Outline



Foot Print

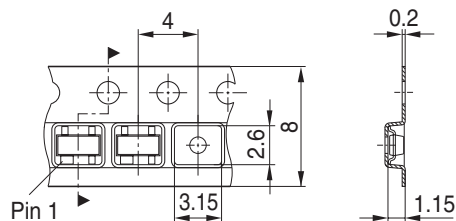


Marking Layout (Example)

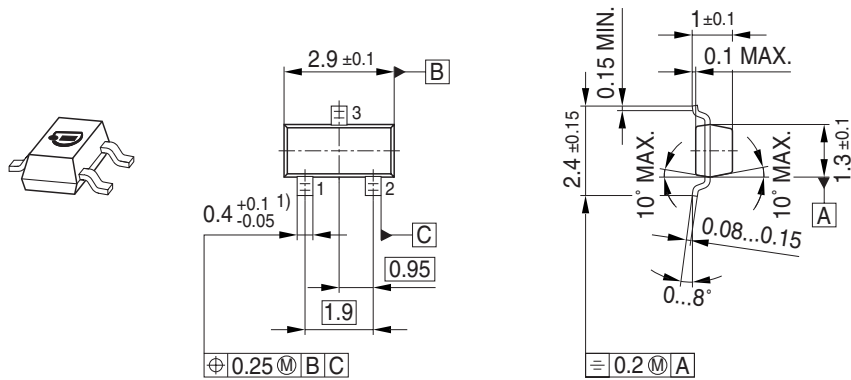


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel

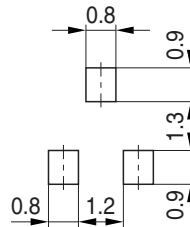


Package Outline

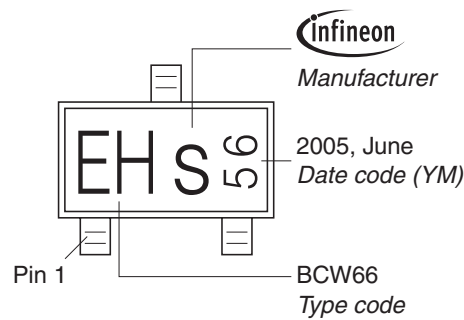


1) Lead width can be 0.6 max. in dambar area

Foot Print

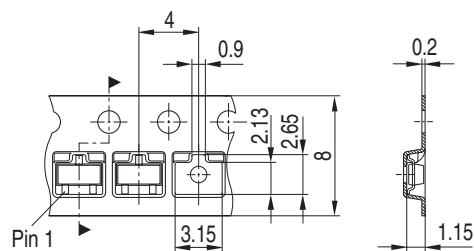


Marking Layout (Example)

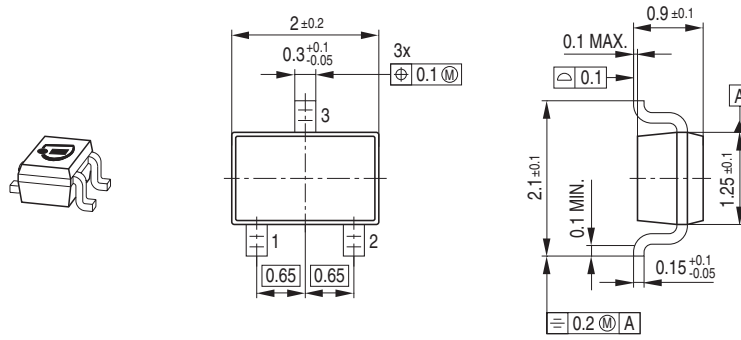


Standard Packing

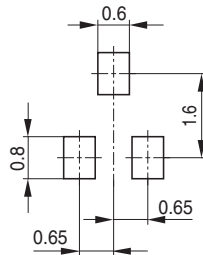
Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel



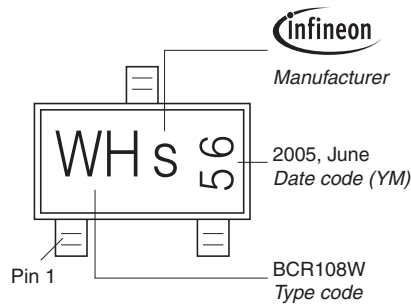
Package Outline



Foot Print

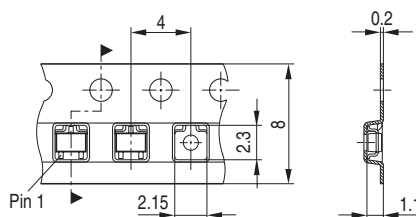


Marking Layout (Example)



Standard Packing

Reel  $\varnothing 180$  mm = 3.000 Pieces/Reel  
 Reel  $\varnothing 330$  mm = 10.000 Pieces/Reel





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